

GSM3497

20V P-Channel Enhancement Mode MOSFET

Product Description

GSM3497, P-Channel enhancement mode MOSFET, uses Advanced Trench Technology to provide excellent $R_{DS(ON)}$, low gate charge.

These devices are particularly suited for low voltage power management, such as smart phone and notebook computer and other battery powered circuits, and low in-line power loss are needed in commercial industrial surface mount applications.

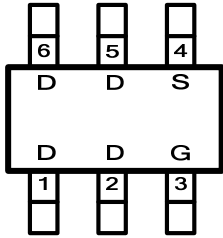
Features

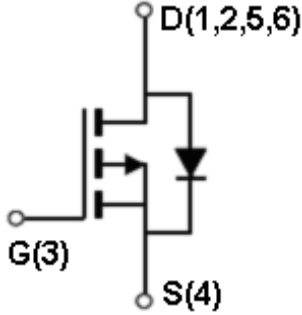
- -20V/-3.8A, $R_{DS(ON)}=100m\Omega@V_{GS}=-4.5V$
- -20V/-2.6A, $R_{DS(ON)}=140m\Omega@V_{GS}=-2.5V$
- -20V/-1.5A, $R_{DS(ON)}=190m\Omega@V_{GS}=-1.8V$
- Super high density cell design for extremely low $R_{DS(ON)}$
- Exceptional on-resistance and maximum DC current capability
- TSOP-6 package design

Applications

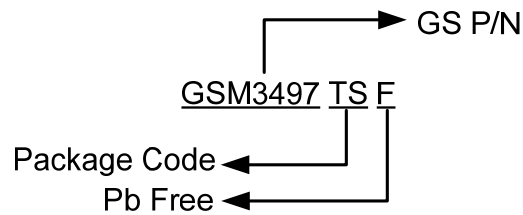
- Power Management in Note book
- Portable Equipment
- Battery Powered System
- Net Working System

Packages & Pin Assignments

GSM3497TSF(TSOP-6)	
	
Pin	Description
1	Drain
2	Drain
3	Gate
4	Source
5	Drain
6	Drain

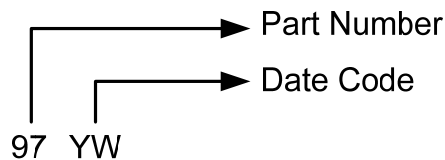


Ordering Information



Part Number	Package	Quantity Reel
GSM3497TSF	TSOP-6	3000 PCS

Marking Information



Absolute Maximum Ratings

$T_A=25^{\circ}\text{C}$, unless otherwise noted

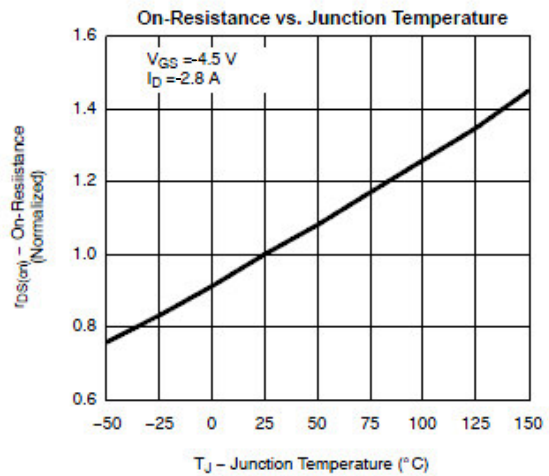
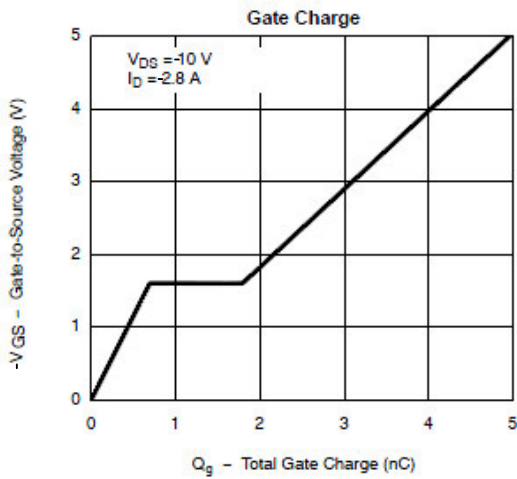
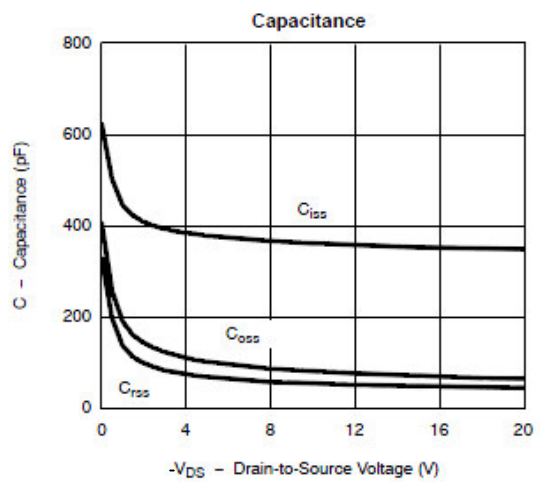
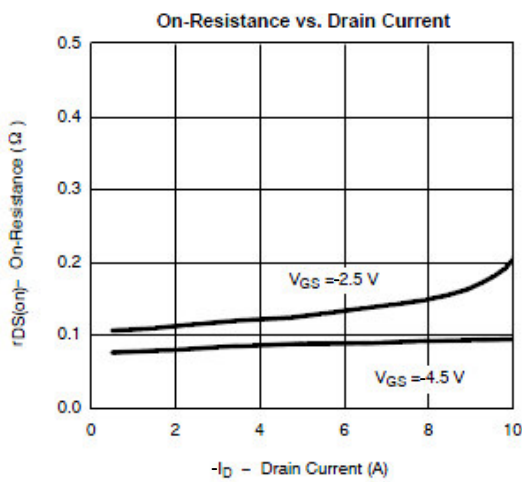
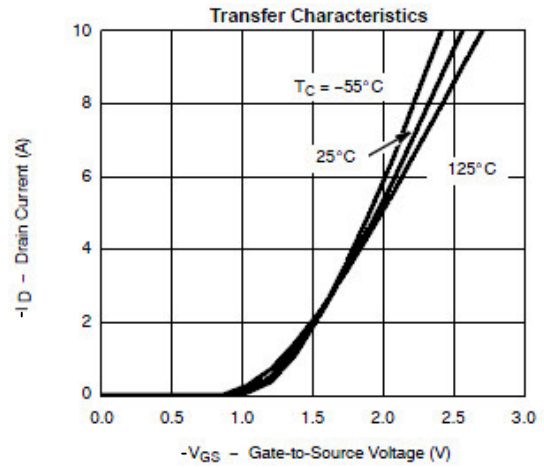
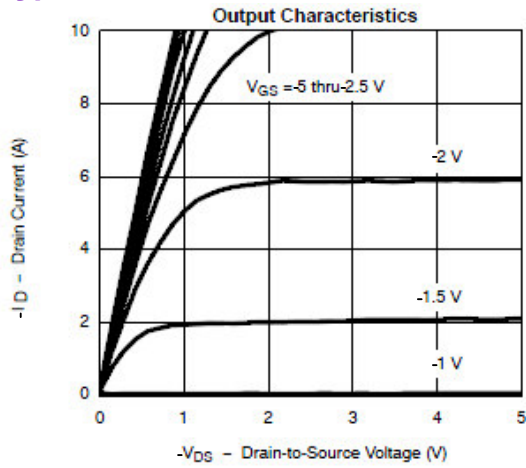
Symbol	Parameter	Typical	Unit	
V_{DSS}	Drain-Source Voltage	-20	V	
V_{GSS}	Gate-Source Voltage	± 12	V	
I_D	Continuous Drain Current($T_J=150^{\circ}\text{C}$)	$T_A=25^{\circ}\text{C}$	-3.8	A
		$T_A=70^{\circ}\text{C}$	-2.6	
I_{DM}	Pulsed Drain Current	-20	A	
I_S	Continuous Source Current(Diode Conduction)	-1.7	A	
P_D	Power Dissipation	$T_A=25^{\circ}\text{C}$	2.0	W
		$T_A=70^{\circ}\text{C}$	1.3	
T_J	Operating Junction Temperature	150	$^{\circ}\text{C}$	
T_{STG}	Storage Temperature Range	-55/150	$^{\circ}\text{C}$	
$R_{\theta JA}$	Thermal Resistance-Junction to Ambient	120	$^{\circ}\text{C}/\text{W}$	

Electrical Characteristics

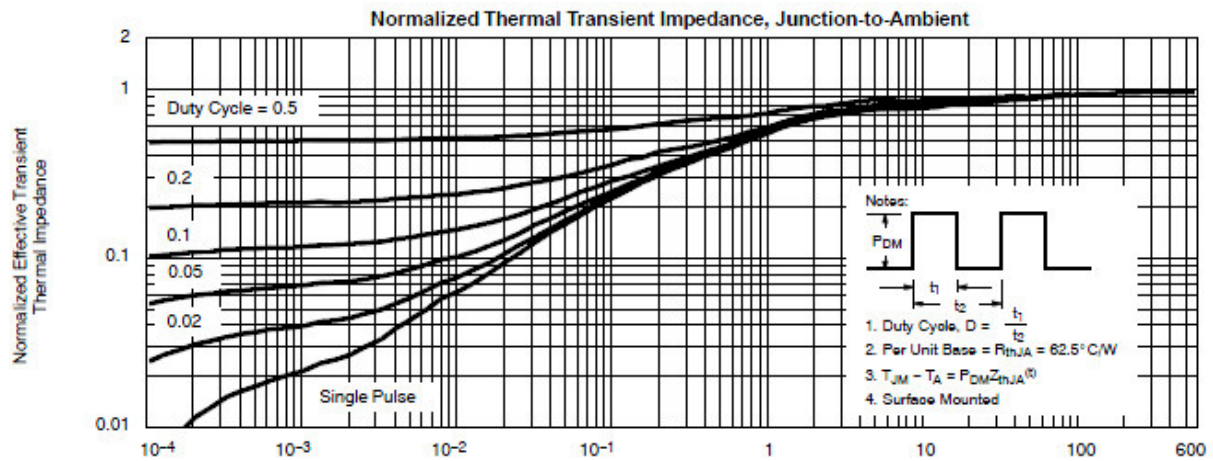
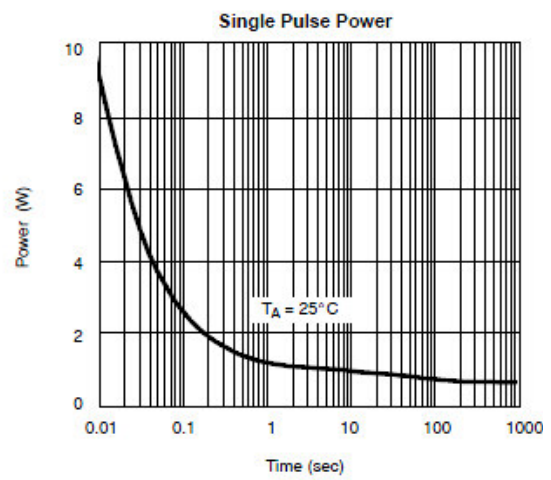
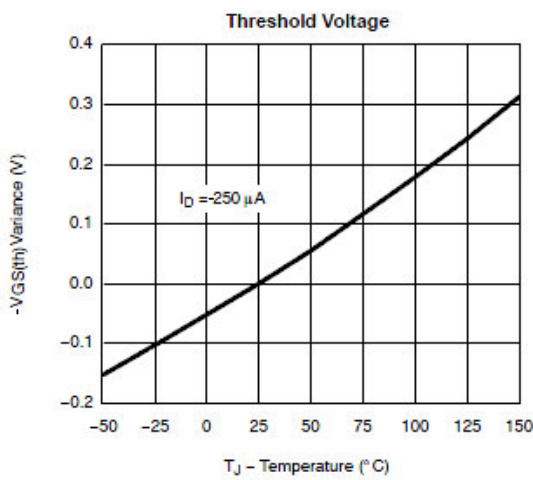
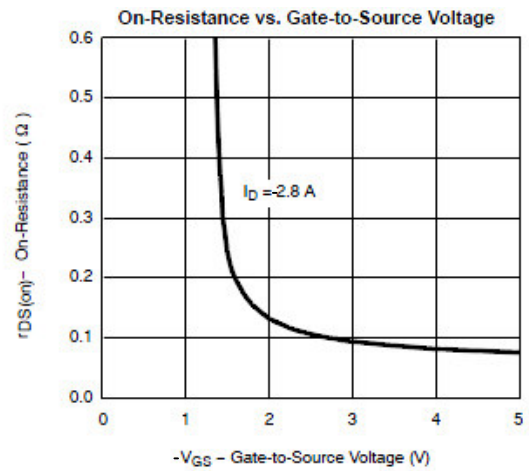
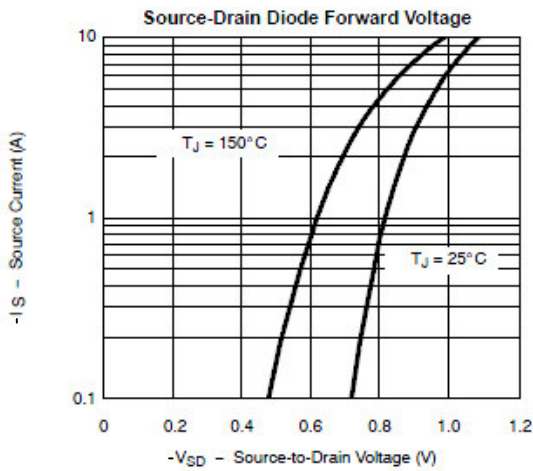
T_A=25°C, unless otherwise noted

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
Static						
V _{(BR)DSS}	Drain-Source Breakdown Voltage	V _{GS} =0V, I _D =-250μA	-20			V
V _{GS(th)}	Gate Threshold Voltage	V _{DS} =V _{GS} , I _D =-250μA	-0.3		-0.7	
I _{GSS}	Gate Leakage Current	V _{DS} =0V, V _{GS} =±12V			±100	nA
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} =-16V, V _{GS} =0V			-1	μA
		V _{DS} =-16V, V _{GS} =0V, T _J =85°C			-30	
I _{D(on)}	On-State Drain Current	V _{DS} ≤ -5V, V _{GS} =-4.5V	-6			A
		V _{DS} ≤ -5V, V _{GS} =-2.5V	-3			
R _{DS(on)}	Drain-Source On-Resistance	V _{GS} =-4.5V, I _D =-3.8A		90	100	mΩ
		V _{GS} =-2.5V, I _D =-2.6A		124	140	
		V _{GS} =-1.8V, I _D =-1.5A		170	190	
g _{FS}	Forward Transconductance	V _{DS} =-5V, I _D =-2.8A		6.5		S
V _{SD}	Diode Forward Voltage	I _S =-1.25A, V _{GS} =0V		-0.75	-1.3	V
Dynamic						
Q _g	Total Gate Charge	V _{DS} =-6V, V _{GS} =-4.5V, I _D =-2.8A		5.8	10	nC
Q _{gs}	Gate-Source Charge			0.85		
Q _{gd}	Gate-Drain Charge			1.7		
C _{iss}	Input Capacitance	V _{DS} =-6V, V _{GS} =0V, f=1MHz		415		pF
C _{oss}	Output Capacitance			223		
C _{rss}	Reverse Transfer Capacitance			87		
t _{d(on)}	Turn-On Time	V _{DD} =-6V, R _L =6Ω, I _D =-1.0A, V _{GEN} =-4.5V, R _G =6Ω		13	25	ns
t _r				36	60	
t _{d(off)}	Turn-Off Time			42	70	
t _f				34	60	

Typical Performance Characteristics

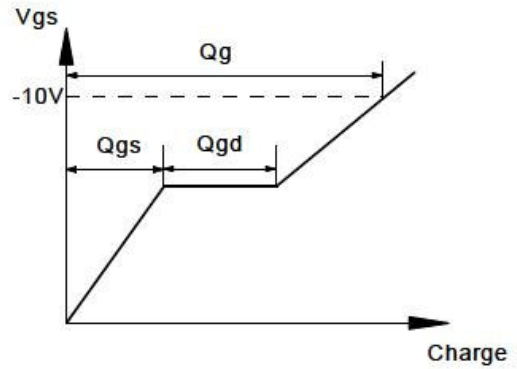
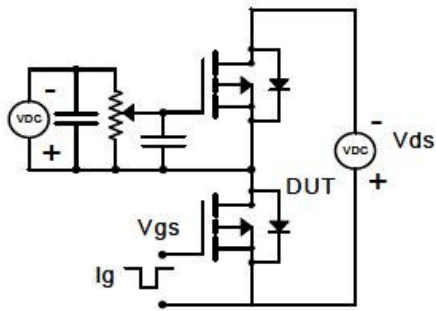


Typical Performance Characteristics (continue)

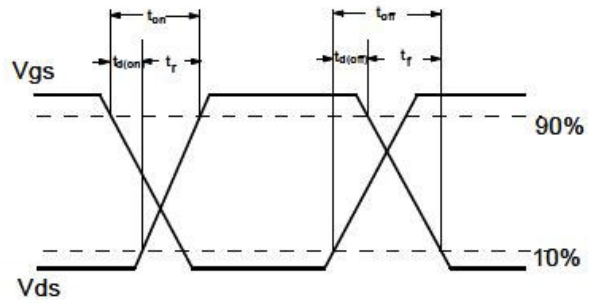
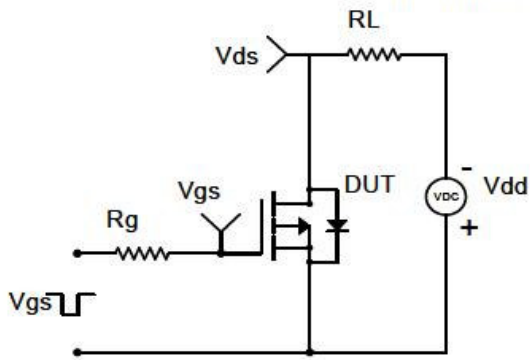


Typical Performance Characteristics (continue)

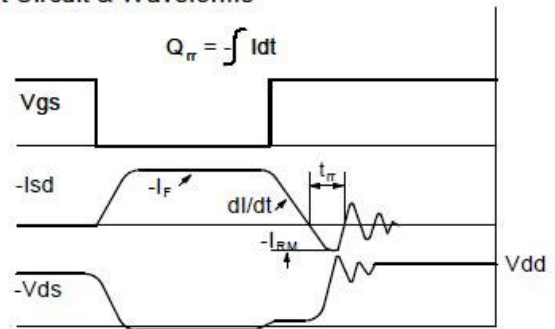
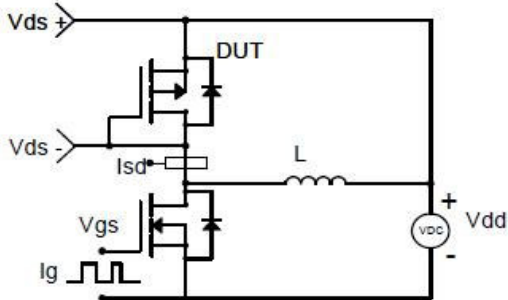
Gate Charge Test Circuit & Waveform



Resistive Switching Test Circuit & Waveforms

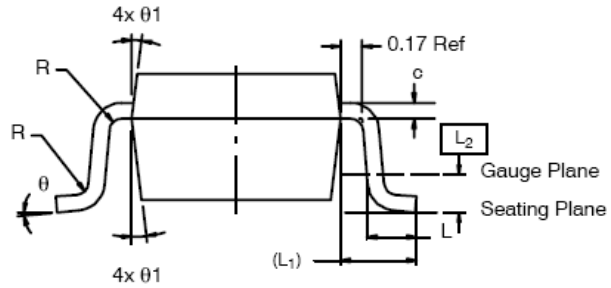
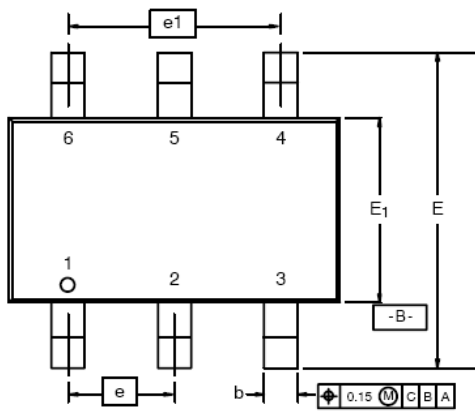


Diode Recovery Test Circuit & Waveforms



Package Dimension

TSOP-6







Symbol	Dimensions In Millimeters			Dimensions In Inches		
	Min	Nom	Max	Min	Nom	Max
A	0.91	-	1.10	0.036	-	0.043
A1	0.01	-	0.10	0.0004	-	0.004
A2	0.90	-	1.00	0.035	0.038	0.039
b	0.30	0.32	0.45	0.012	0.013	0.018
c	0.10	0.15	0.20	0.004	0.006	0.008
D	2.95	3.05	3.10	0.116	0.120	0.122
E	2.70	2.85	2.98	0.106	0.112	0.117
E1	1.55	1.65	1.70	0.061	0.065	0.067
e	1.00 BSC			0.0394 BSC		
e1	1.90	2.00	2.10	0.075	0.080	0.085
L	0.35	-	0.50	0.014	-	0.020
L1	0.60 Ref			0.024 Ref		
L2	0.25 BSC			0.010 BSC		
R	0.10	-	-	0.004	-	-
θ	0°	4°	8°	0°	4°	8°
θ1	7° Nom			7° Nom		



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